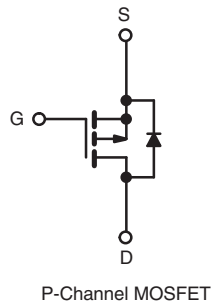
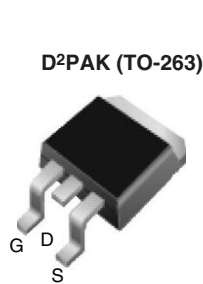


Power MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	- 100	
$R_{DS(on)}$ (Ω)	$V_{GS} = - 10$ V	0.20
Q_g (Max.) (nC)	61	
Q_{gs} (nC)	14	
Q_{gd} (nC)	29	
Configuration	Single	



FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Surface Mount
- Available in Tape and Reel
- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- P-Channel
- 175 °C Operating Temperature
- Fast Switching
- Compliant to RoHS Directive 2002/95/EC



RoHS*
COMPLIANT
HALOGEN
FREE
Available

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D²PAK (TO-263) is a surface mount power package capable of accommodating die sizes up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The D²PAK (TO-263) is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0 W in a typical surface mount application.

ORDERING INFORMATION

Package	D ² PAK (TO-263)	D ² PAK (TO-263)
Lead (Pb)-free and Halogen-free	SiHF9540S-GE3	SiHF9540STRL-GE3 ^a
Lead (Pb)-free	IRF9540SPbF SiHF9540S-E3	IRF9540STRLPbF ^a SiHF9540STL-E3 ^a

Note

- a. See device orientation.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	- 100	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	V_{GS} at - 10 V	$T_C = 25$ °C	- 19
		$T_C = 100$ °C	- 13
Pulsed Drain Current ^a	I_{DM}	- 72	A
Linear Derating Factor		1.0	W/°C
Linear Derating Factor (PCB Mount) ^e		0.025	
Single Pulse Avalanche Energy ^b	E_{AS}	640	mJ
Repetitive Avalanche Current ^a	I_{AR}	- 19	A
Repetitive Avalanche Energy ^a	E_{AR}	15	mJ
Maximum Power Dissipation	$T_C = 25$ °C	150	W
Maximum Power Dissipation (PCB Mount) ^e		3.7	
Peak Diode Recovery dV/dt ^c	dV/dt	- 5.5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 175	°C
Soldering Recommendations (Peak Temperature)	for 10 s	300 ^d	

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = - 25$ V, starting $T_J = 25$ °C, $L = 2.7$ mH, $R_g = 25$ Ω , $I_{AS} = - 19$ A (see fig. 12).
- $I_{SD} \leq - 19$ A, $dI/dt \leq 200$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 175$ °C.
- 1.6 mm from case.
- When mounted on 1" square PCB (FR-4 or G-10 material)

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient (PCB Mount) ^a	R _{thJA}	-	-	40	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	-	1.0		

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

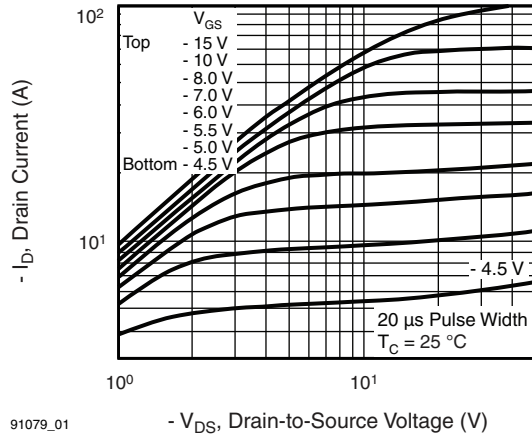
SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA		- 100	-	-	V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = - 1 mA		-	- 0.087	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA		- 2.0	-	- 4.0	V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 100 V, V _{GS} = 0 V		-	-	- 100	μA
		V _{DS} = - 80 V, V _{GS} = 0 V, T _J = 150 °C		-	-	- 500	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = - 10 V	I _D = - 11 A ^b	-	-	0.20	Ω
Forward Transconductance	g _{fs}	V _{DS} = - 50 V, I _D = - 11 A		6.2	-	-	S
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = - 25 V, f = 1.0 MHz, see fig. 5		-	1400	-	pF
Output Capacitance	C _{oss}			-	590	-	
Reverse Transfer Capacitance	C _{rss}			-	140	-	
Total Gate Charge	Q _g	V _{GS} = - 10 V	I _D = - 19 A, V _{DS} = - 80 V, see fig. 6 and 13 ^b	-	-	61	nC
Gate-Source Charge	Q _{gs}			-	-	14	
Gate-Drain Charge	Q _{gd}			-	-	29	
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 50 V, I _D = - 19 A, R _G = 9.1 Ω, R _D = 2.4 Ω, see fig. 10 ^b		-	16	-	ns
Rise Time	t _r			-	73	-	
Turn-Off Delay Time	t _{d(off)}			-	34	-	
Fall Time	t _f			-	57	-	
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nH
Internal Source Inductance	L _S			-	7.5	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	- 19	A
Pulsed Diode Forward Current ^a	I _{SM}			-	-	- 72	
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = - 19 A, V _{GS} = 0 V ^b		-	-	- 5.0	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = - 19 A, di/dt = 100 A/μs ^b		-	130	260	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	0.35	0.70	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)					

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

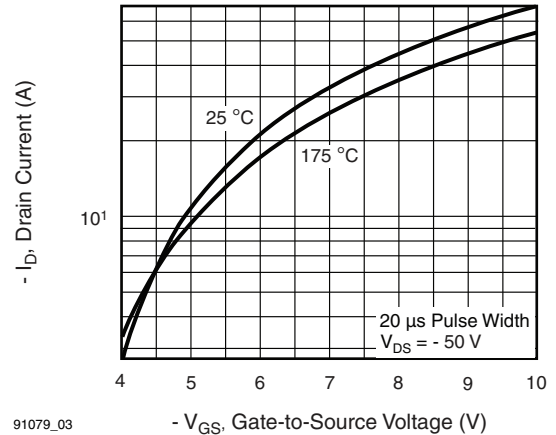
b. Pulse width ≤ 300 μs; duty cycle ≤ 2 %.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



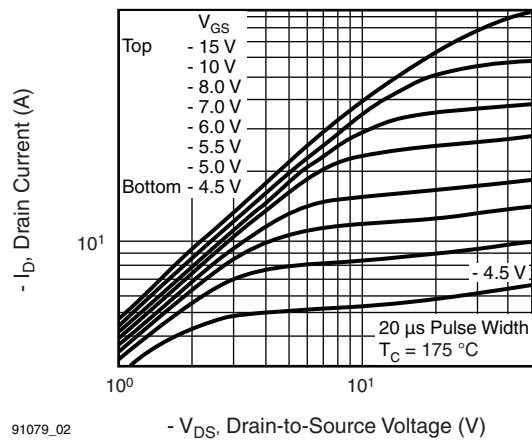
91079_01

Fig. 1 - Typical Output Characteristics, $T_C = 25\text{ }^\circ\text{C}$



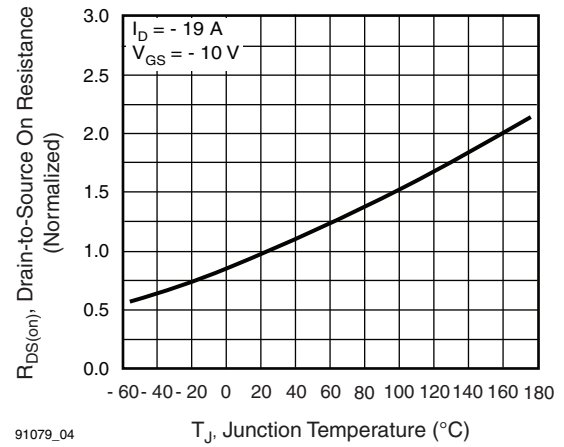
91079_03

Fig. 3 - Typical Transfer Characteristics



91079_02

Fig. 2 - Typical Output Characteristics, $T_C = 175\text{ }^\circ\text{C}$



91079_04

Fig. 4 - Normalized On-Resistance vs. Temperature



Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

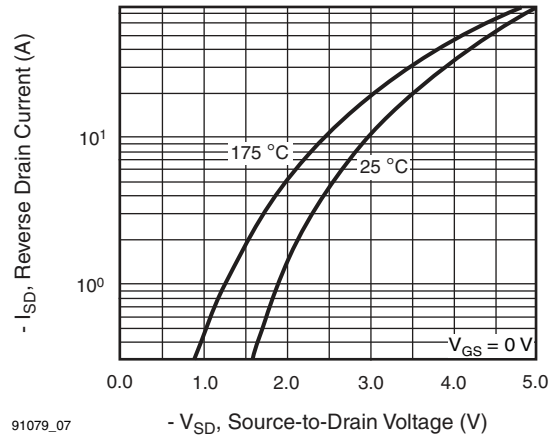


Fig. 7 - Typical Source-Drain Diode Forward Voltage

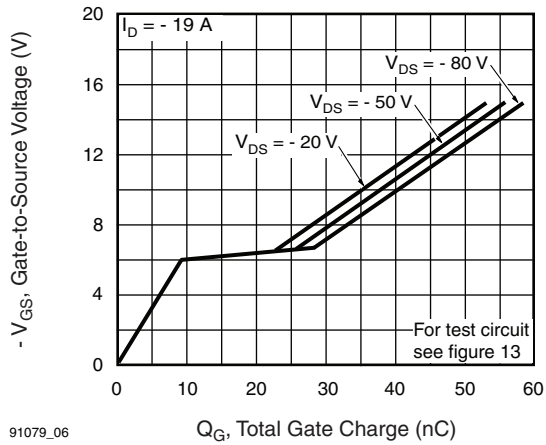


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

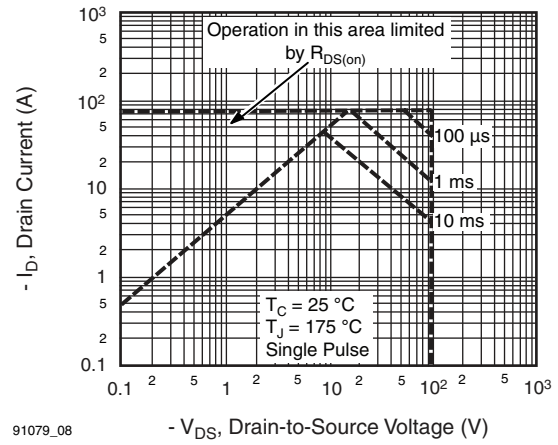


Fig. 8 - Maximum Safe Operating Area



Fig. 9 - Maximum Drain Current vs. Case Temperature

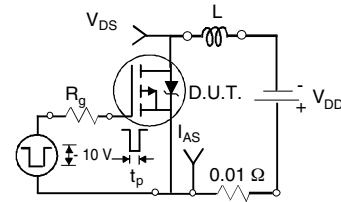


Fig. 10a - Switching Time Test Circuit

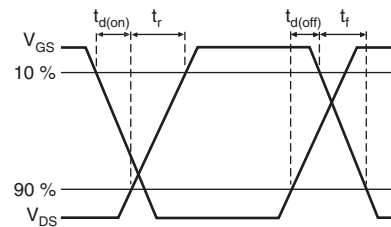


Fig. 10b - Switching Time Waveforms

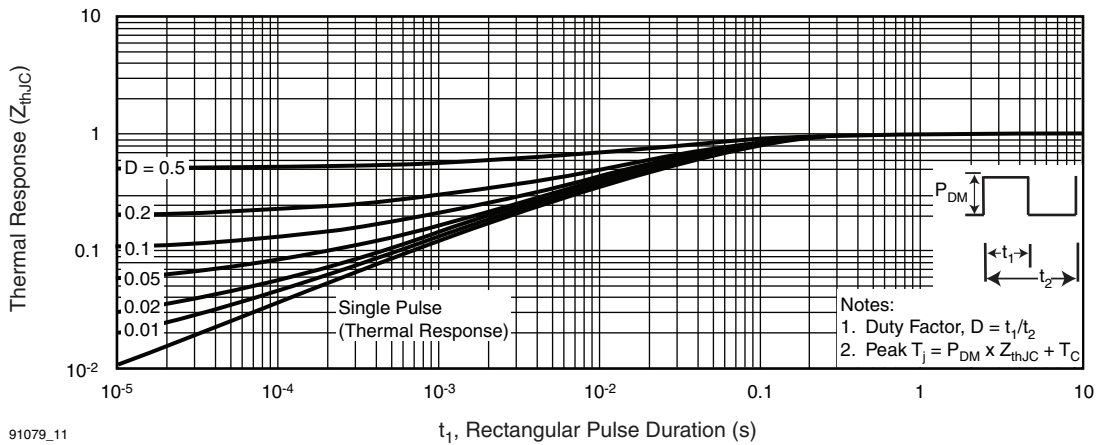


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

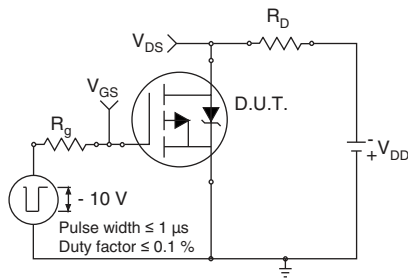


Fig. 12a - Unclamped Inductive Test Circuit



Fig. 12b - Unclamped Inductive Waveforms



91079_12c

Fig. 12c - Maximum Avalanche Energy vs. Drain Current

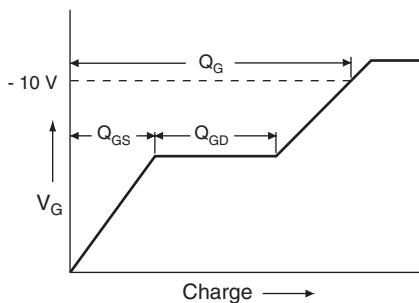


Fig. 13a - Basic Gate Charge Waveform

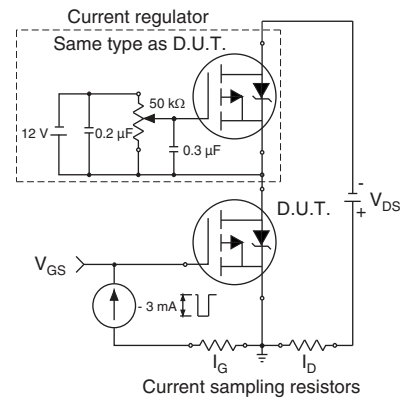
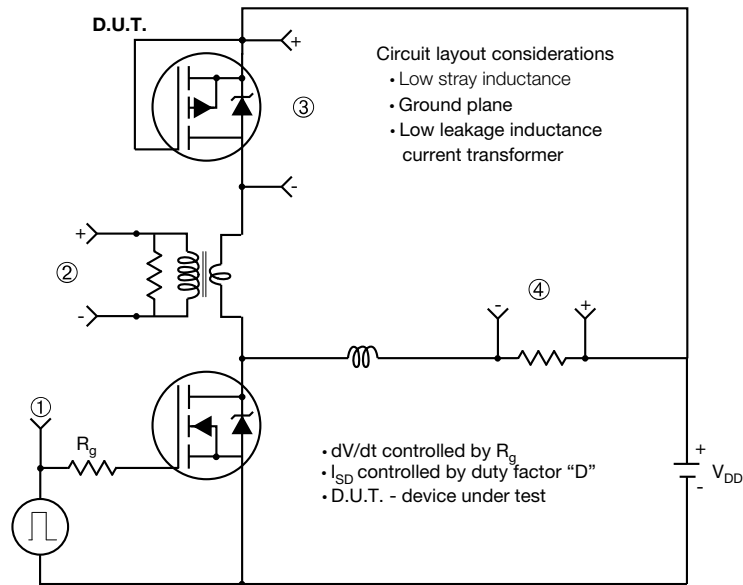


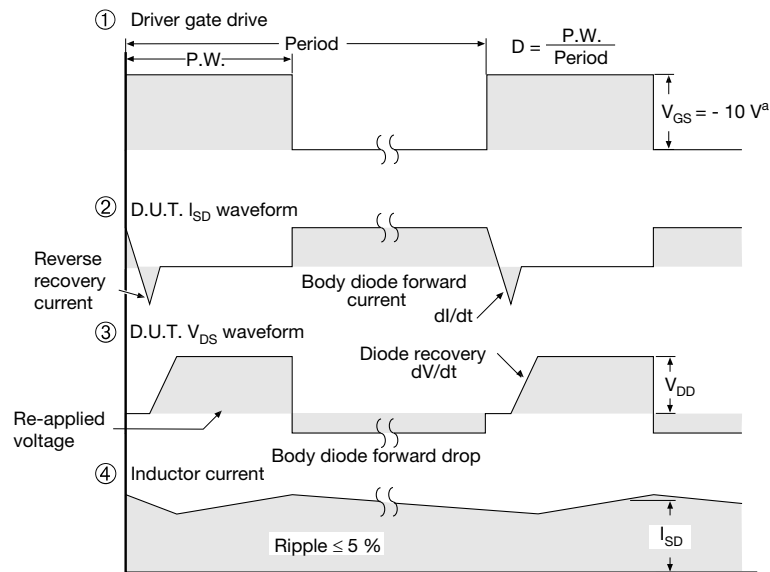
Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



Note

- Compliment N-Channel of D.U.T. for driver



Note

a. $V_{GS} = -5\text{ V}$ for logic level and -3 V drive devices

Fig. 14 - For P-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91079.

TO-263AB (HIGH VOLTAGE)



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
c	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	-	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010 BSC	
L4	4.78	5.28	0.188	0.208

ECN: S-82110-Rev. A, 15-Sep-08
DWG: 5970

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.



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